

## Soder-Wick® No Clean Desoldering Braid

### Product Description

Soder-Wick No Clean is designed to provide fast and safe desoldering without leaving behind harmful flux residues. Soder-Wick No Clean uses pure, oxygen free copper braid and a patented flux technology to make an efficient and effective desoldering braid. Soder-Wick No Clean SD is available on ESD safe bobbins for protection against damage due to static electricity.

- Requires little or no post solder cleaning
- No corrosive residues
- Halide free
- ESD Safe bobbins meet specs:
  - MIL-STD-1686C
  - MIL-HDBK-263B
  - Static decay provision of MIL-B-81705C
- Minimal risk of heat and static component damage

### Typical Applications

Soder-Wick No Clean safely removes solder from:

- Lugs and Posts
- Micro Circuits
- Surface Mount Device Pads
- Ball Grid Array Pads

### Soder-Wick No Clean Meets or Exceeds:

- MIL-F-14256F, Type R
- DOD-STD-883E, Method 2022
- Bellcore TR-NWT-000078
- ANSI/IPC J SF-818



### Typical Product Data and Physical Properties

Surface Insulation Resistance			
<b>Bellcore TR-NWT-000078 : PASS</b>			
After 96 Hours (megohms) $2 \times 10^4$ Limit			
<u>Group A</u>	<u>Group B</u>	<u>Group C</u>	
$4.8 \times 10^6$	$3.8 \times 10^6$	$4.1 \times 10^6$	
<b>ANSI/IPC J SF-818 : PASS</b>			
After 168 Hours (ohms) $1.8 \times 10^8$ Limit			
<u>1-2</u>	<u>2-3</u>	<u>3-4</u>	<u>4-5</u>
$2.3 \times 10^{10}$	$2.6 \times 10^6$	$2.8 \times 10^6$	$2.8 \times 10^{10}$
<b>Electromigration : PASS</b>			
Average Insulation Resistance (megohms)-One Decade Limit			
	Initial	Final	
Group E	$3.93 \times 10^3$	$1.24 \times 10^4$	
Group F	$3.87 \times 10^3$	$2.84 \times 10^4$	
At 10x magnification no evidence of electromigration or heavy corrosion.			
<b>Silver Chromate Test Paper</b>	<b>PASS</b>		
<b>Copper Mirror Test</b>	<b>PASS</b>		
<b>Shelg Life:</b>	2 years		
<b>RoHS Compliant</b>	Yes		

## Soder-Wick® No Clean Desoldering Braid

### Usage Instructions

**For industrial use only. Read SDS carefully prior to use.**

- 1) Choose a Soder-Wick® No Clean width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F.
- 4) Place wick on solder joint and place tip of hot iron on top of wick.
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard used portion of the wick

Size #	Size Inches	Color	Size Metric
1	.030"	White	.76mm
2	.060"	Yellow	1.52mm
3	0.80"	Green	2.03mm
4	.110"	Blue	2.79mm
5	.145"	Brown	3.68mm
6	.210"	Red	5.33mm

### Availability

25 bobbins per bag.

Part #	Size #	Length	Part#	Size	Length
60-1-5	1	5	60-1-10	1	10
60-2-5	2	5	60-2-10	2	10
60-3-5	3	5	60-3-10	3	10
60-4-5	4	5	60-4-10	4	10
60-5-5	5	5	60-5-10	5	10
60-6-5	6	5			

Resealable Packaging	Part #	Size
	SW16025	2
	SW16035	3
	SW16045	4

The resealable bag contains ten five-foot bobbins. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

### Technical and Application Assistance

Chemtronics provides a technical hotline to answer your technical and application related questions.

*The toll free number is: 1-800-TECH-401.*

### Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

Chemtronics®, Soder-Wick® and CircuitWorks® are registered trademarks of Chemtronics. All rights reserved.